

PATENT ASSIGNMENT

Electronic Version v1.1

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Jun-Chung Hsu	06/25/2009
Chen-Lin Li	06/25/2009
RECEIVING PARTY DATA	
Name:	Kinsus Interconnect Technology Corp.
Street Address:	No. 1245, Junghua Rd.
Internal Address:	Shin-Wu Shiang
City:	Taoyuan
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12493171
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	09188URL
NAME OF SUBMITTER:	Jason Z. Lin
Total Attachments: 1 source=09188URL-Assignment#page1.tif	

OP \$40.00 12493171

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PATENT
REEL: 022884 FRAME: 0447

ASSIGNMENT

WHEREAS, I/we, Hsu, Jun-Chung and Li, Chen-Lin,
whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful
improvements in Package Structure Preventing Solder Overflow On Substrate Solder Pads
(hereinafter referred to as the Invention) for which an application for United States Letters Patent was

- ☒ executed on even date herewith;
☐ executed on _____;
☐ filed on _____, Serial No. _____;
☐ filed as PCT International Application No. _____ on _____, designating
The United States of America;
☐ Patent number _____, issue on _____.

WHEREAS, KINSUS INTERCONNECT TECHNOLOGY CORP.,
whose post office address is No. 1245, Junghua Rd., Shin-Wu Shiang, Taoyuan, Taiwan
hereinafter referred to as ASSIGNEE, is desirous of acquiring the entire right, title and interest in and to the same in the United
States;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, I/we, ASSIGNOR,
by these presents do sell, assign and transfer unto said ASSIGNEE, the entire right, title, and interest in and to said invention
and application throughout the United States of America, including any and all Letters Patent granted on any division,
continuation, continuation-in-part and reissue of said application.

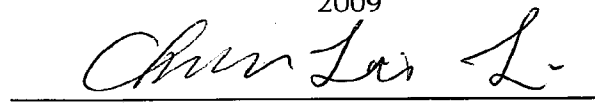
ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing,
prosecution and maintenance of said application or any other patent application(s) in the United States for said invention,
including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without
further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and
communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the invention that are within
ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may
be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent
encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's
heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Director of Patents and Trademarks to issue any and all Letters
Patent referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for
ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full
end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by
ASSIGNOR had this assignment and sale not been made.

Assignor: Hsu, Jun-Chung Dated this 25th day of June, at Taiwan
No. 11, Lane 192, Kuang-Te Street, 2009
Fu-Hsing Li, Ping-Chen City,
Taoyuan Hsien, Taiwan


Signature

Assignor: Li, Chen-Lin Dated this 25th day of June, at Taiwan
No. 33, Chih-Ping Road, 2009
Tsai-Chiao Li,
E. Dist.,
Hsinchu City, Taiwan


Signature

Assignor: Dated this day of at

Signature